

INDUSTRIAL STRENGTH... Start Your Application From YOURITECH

Integration support

Obsolescence Management

PCAP

Embedded Systems

Human Machine Interface

Touch Solutions

Software

Quality Management

Open Frame Monitors

LCD Controller

Research & Development

Firmware

EMC tests

on-site service

Optical Bonding

In-house Manufacturing

Cover glass

System solutions

OEM Solutions

Custom Display

Production Custom designs Installation

Mechanical design



Project No. 项目编号	ET021WV01-TT
Customer 客户名称	
Module No. 客户型号	
Product type 产品内容	Standard LCD Module TFT: 480*RGBx480Dots 2.1" TFT LCD+CTP

客户确认 Customer Approval	
项目负责人 Project Manager	
品质主管 Director of Quality	
采购工程师 Purchasing Engineer	

PREPARED BY	CHECKED BY	APPROVED BY



1. Introduction

1.1 Scope of application

This specification applies to the LCD module that is supplied by YOURITECH Technology CO., LTD.

LCD specification: Dots 480xRGBx480

As to basic specification of the driver IC, refer to the IC (Sitronix: ST7701S) specification and data book.

All material & processing of the LCD module should be Lead Free.

1.2 TFT features:

Structure: TFT PANNEL+IC +FPC+BL+CTP;

ALL Viewing Type LCD

480 dot-segment and 480 dot-common outputs;

16.7M Color can be selected by software;

White LED back light;

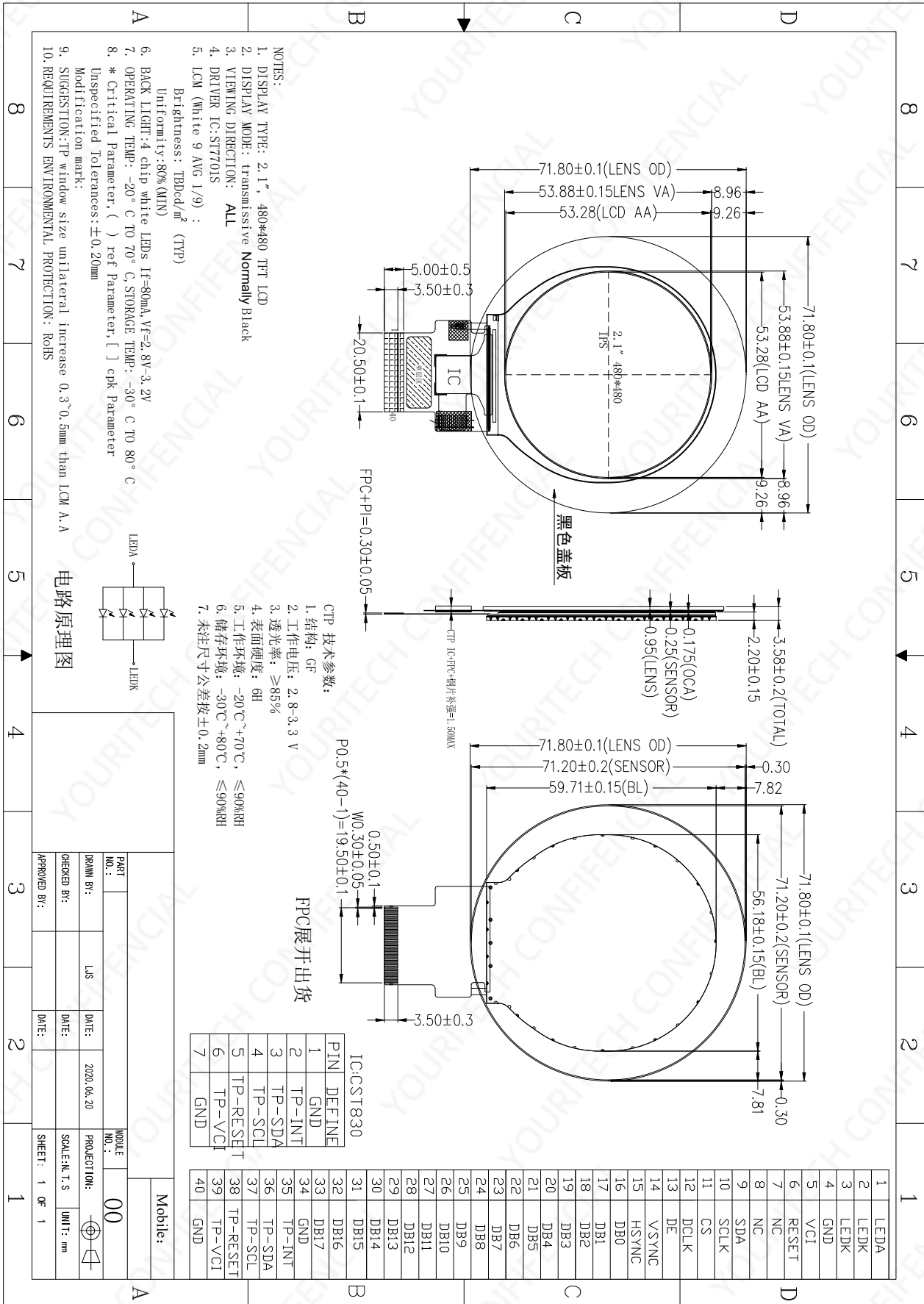
18bit RGB interface



2. LCM General specification

ITEM	Standard value	Unit
LCD Type	Normally Black	--
Drive element	TFT active matrix	--
Number of pixels	480*3RGB(H)X480(V)	Dots
Pixel arrangement	RGB Vertical Stripe	--
Pixel Pitch (W*H)	0.111(H) × 0.111(V)	mm
Active area	53.28(H) x 53.28(V)	mm
Viewing direction	ALL Viewing	-
TFT Driver IC	ST7701S	
TFT interface	18bit RGBI Interface	-
Approx. Weight	TBD	g
LCM Size(W*H*T)	56.18(W) ×59.71(H) ×2.20(T)	mm
LCM+CTP Size(W*H*T)	71.80(W) ×71.80(H) ×3.58(T)	mm
Touch structure	G+F	
Touch Driver IC	CST830	-
Touch Interface	I2C	





3.Absolute Maximum Rating

Characteristics	Symbol	Min.	Max.	Unit
LCM Operating Temperature	T _{OPR}	-20	+70	°C
LCM Storage Temperature	T _{STG}	-30	+80	°C
CTP Operating Temperature & Humidity (20% ~ 90%RH)	T _{OPR}	-20	+70	°C
CTP SStorage Temperature & Humidity (20% ~ 90%RH)	T _{STG}	-30	+80	°C
Humidity	RH	-	90	%

4.Electrical Characteristics

4.1 TFT DC Characteristics

Characteristics	Symbol	Min.	Typ.	Max.	Unit
Supply Voltage for I/O	IOVCC	--	--	--	V
Supply Voltage for(DC/DC)	VCC	2.6	2.8	3.3	V

4.2 Back-Light Unit Characeristics

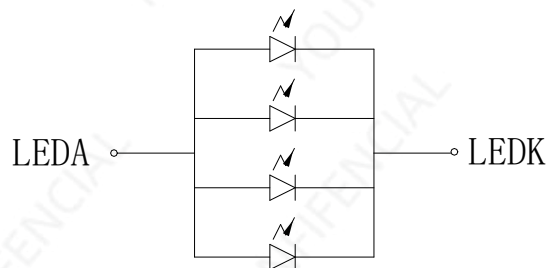
The back-light system is an edge-lighting type with4 white LEDs. The characteristics of the back-light are shown in the following tables.

Characteristics	Symbol	Min.	Type	Max.	Unit	Notes
Forward Voltage	V _F	2.8	--	3.2	V	-
Forward current	I _F	--	80	-	mA	-
Luminance(With LCD+CTP)	L _v	--	TBD	--	cd/m ²	-
LED life time	N/A	--	30,000	--	Hr	Note 1

Note:

- (1) The “LED life time” is defined as the module brightness decrease to 50% of original brightness at I_L=20mA/LED. The LED life time could be decreased if operating I_L is larger than 25mA/LED.

Backlight circuit diagram shown in below:



5. Module Function Description

Pin No.	Symbol	LCM Functional	Notes
1	LEDA	Power supply for backlight anode input terminal.	
2	LEDK	Power supply for backlight cathode input terminal.	
3	LEDK	Power supply for backlight cathode input terminal.	
4	GND	Power Ground	
5	VC1	Power supply : 2.6V ~ 3.3V	
6	RESET	Reset signal input terminal. Active at 'L'.	
7	NC	NC	
8	NC	NC	
9	SDA	Input/Output signal pin	
10	SCK	Serial interface clock	
11	CS	Chip select signal input pin	
12	PCLK	Dot clock signal for RGB interface operation.	
13	DE	Data enable signal for RGB interface operation.	
14	VSYNC	Vertical (Frame) synchronizing input signal for RGB interface operation.	
15	HSYNC	Horizontal (Line) synchronizing input signal for RGB interface operation.	
16~33	DB0~DB17	RGB interface data bus.	
34	GND	Power Ground	
35	CTP_INT	Touch panel interrupt output	
36	CTP_SDA	Touch panel I2C data	
37	CTP_SCL	Touch panel I2C clock	
38	CTP_RST	Touch panel reset	
39	CTP_VCI	Touch panel Power supply 2.8~3.3V	
40	GND	Power Ground	



6. Timing Characteristics

POWER ON/OFF SEQUENCE

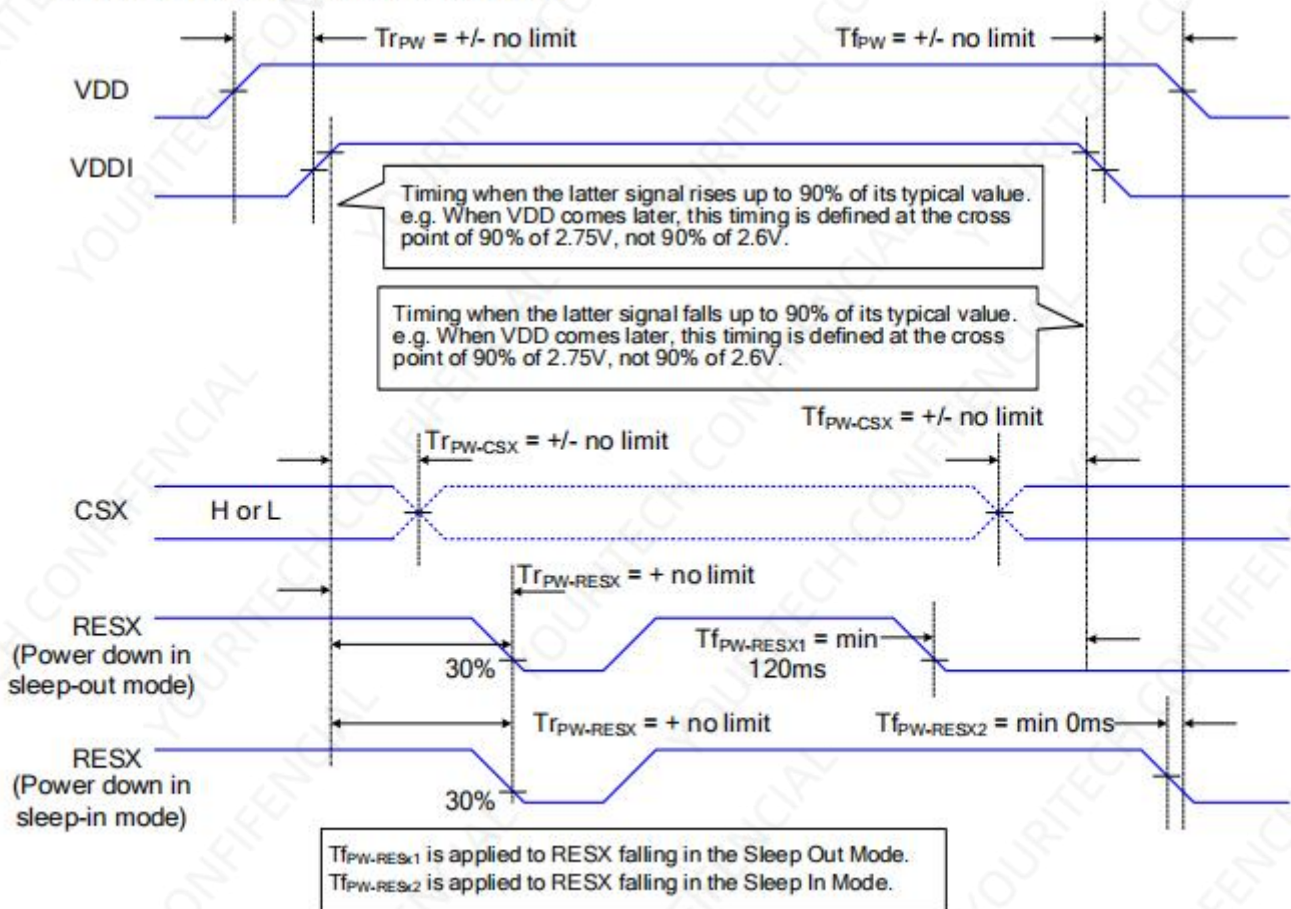
VDDI and VDDA can be applied or powered down in any order. During the Power Off sequence, if the LCD is in the Sleep Out mode, VDDA and VDDI must be powered down with minimum 120msec. If the LCD is in the Sleep In mode, VDDA and VDDI can be powered down with minimum 0msec after the RESX is released.

CSX can be applied at any timing or can be permanently grounded. RESX has high priority over CSX.

Notes:

1. There will be no damage to the ST7701S if the power sequences are not met.
2. There will be no abnormal visible effects on the display panel during the Power On/Off Sequences.
3. There will be no abnormal visible effects on the display between the end of Power On Sequence and before receiving the Sleep Out command, and also between receiving the Sleep In command and the Power Off Sequence.
4. If the RESX line is not steadily held by the host during the Power On Sequence as defined in Sections 9.1 and 9.2, then it will be necessary to apply the Hardware Reset (RESX) after the completion of the Host Power On Sequence to ensure correct operations. Otherwise, all the functions are not guaranteed.

The power on/off sequence is illustrated below



Serial Interface Characteristics (3-line serial):

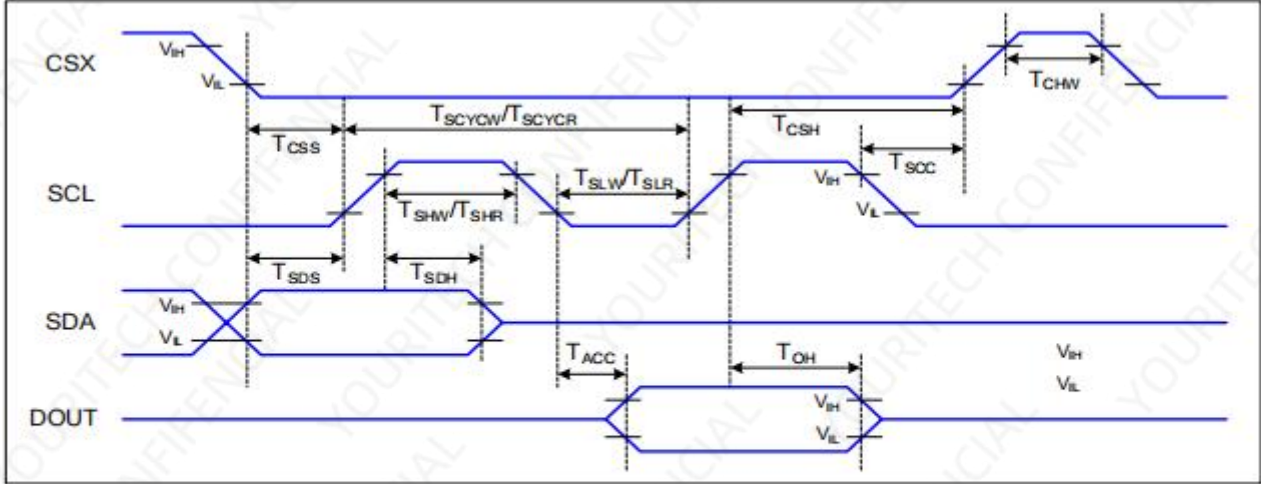


Figure 1 3-line serial Interface Timing Characteristics

VDDI=1.8, VDD=2.8, AGND=DGND=0V, T_a=25℃

Signal	Symbol	Parameter	Min	Max	Unit	Description
CSX	T _{CSS}	Chip select setup time (write)	15		ns	
	T _{CSH}	Chip select hold time (write)	15		ns	
	T _{CSS}	Chip select setup time (read)	60		ns	
	T _{SOC}	Chip select hold time (read)	60		ns	
	T _{CHW}	Chip select "H" pulse width	40		ns	
SCL	T _{SCYCW}	Serial clock cycle (Write)	66		ns	
	T _{SHW}	SCL "H" pulse width (Write)	15		ns	
	T _{SLW}	SCL "L" pulse width (Write)	15		ns	
	T _{SCYCR}	Serial clock cycle (Read)	150		ns	
	T _{SHR}	SCL "H" pulse width (Read)	60		ns	
	T _{SLR}	SCL "L" pulse width (Read)	60		ns	
SDA (DIN)	T _{SDS}	Data setup time	10		ns	
	T _{SDH}	Data hold time	10		ns	

Table 4 3-line serial Interface Characteristics

Note : The rising time and falling time (Tr, Tf) of input signal are specified at 15 ns or less. Logic high and low levels are specified as 30% and 70% of VDDI for Input signals.



RGB Interface Characteristics :

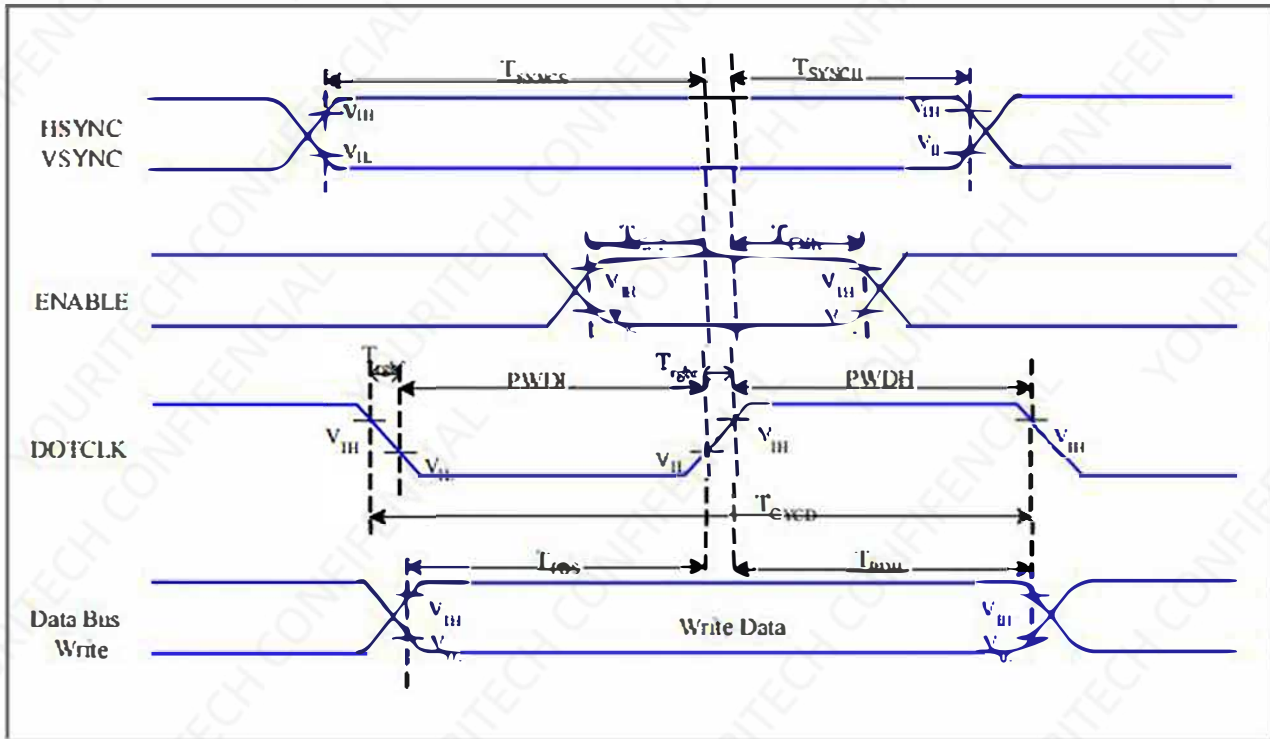


Figure 3 RGB Interface Timing Characteristics

$VDD=1.8, VDD=2.8, AGND=DGND=0V, T_a=25\text{ }^{\circ}\text{C}$

Signal	Symbol	Parameter	MIN	MAX	Unit	Description
HSYNC, VSYNC	T_{syncs}	VSYSN. HSYNC Setup Time	5	-	ns	
ENABLE	T_{ens}	Enable Setup Time	5	-	ns	
	T_{enh}	Enable Hold Time	5	-	ns	
DOTCLK	PWDH	DOTCLK High-level Pulse Width	15	-	ns	
	PWDL	DOTCLK Low-level Pulse Width	15	-	ns	
	T_{cyd}	DOTCLK Cycle Time	33	-	ns	
	$Trghr, Trghf$	DOTCLK Rise/Fall time	-	15	ns	
DB	T_{pdS}	PD Data Setup Time	5	-	ns	
	T_{pdH}	PD Data Hold Time	5	-	ns	

Table 6 18/16 Bits RGB Interface Timing Characteristics



Reset Description:

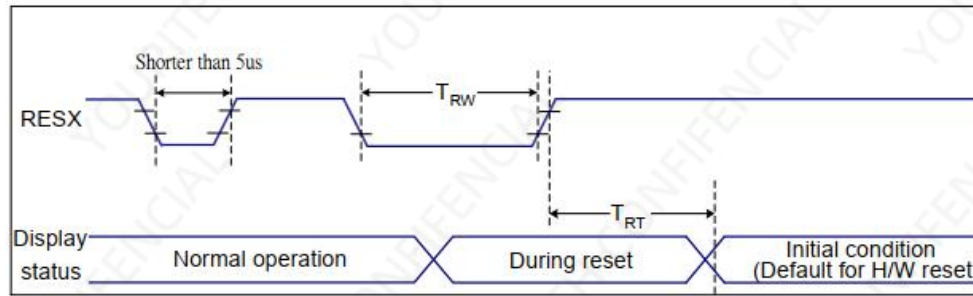


Figure 9 Reset Timing

VDDI=1.8, VDD=2.8, AGND=DGND=0V, Ta=25 °C

Related Pins	Symbol	Parameter	MIN	MAX	Unit
RESX	TRW	Reset pulse duration	10	-	us
	TRT	Reset cancel	-	5 (Note 1, 5)	ms
				120 (Note 1, 6, 7)	ms

Table 9 Reset Timing

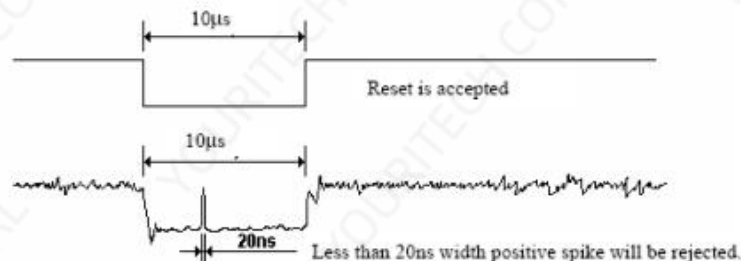
Notes:

1. The reset cancel includes also required time for loading ID bytes, VCOM setting and other settings from NVM (or similar device) to registers. This loading is done every time when there is HW reset cancel time (tRT) within 5 ms after a rising edge of RESX.
2. Spike due to an electrostatic discharge on RESX line does not cause irregular system reset according to the table below:

RESX Pulse	Action
Shorter than 5us	Reset Rejected
Longer than 9us	Reset
Between 5us and 9us	Reset starts

3. During the Resetting period, the display will be blanked (The display is entering blanking sequence, which maximum time is 120 ms, when Reset Starts in Sleep Out –mode. The display remains the blank state in Sleep In –mode.) and then return to Default condition for Hardware Reset.

4. Spike Rejection also applies during a valid reset pulse as shown below:



5. When Reset applied during Sleep In Mode.
6. When Reset applied during Sleep Out Mode.
7. It is necessary to wait 5msec after releasing RESX before sending commands. Also Sleep Out command cannot be sent for 120msec.



7.Optical Characteristics

Optical Specification

Parameter		Symbol	Condition	Min.	Typ.	Max.	Unit	Remark
Viewing Angle	Horizontal	Θ3	CR> 10	80	85		°	Note 1
		Θ9		80	85		°	
	Vertical	Θ12		80	85		°	
		Θ6		80	85		°	
Contrast Ratio		CR	Θ= 0°	800:1	1000:1			Note 2
Transmittance		T(%)	Θ= 0°	3.6	4.0			Note 3
NTSC		%	Θ= 0°	64	69			
Reproduction Of color	Red	Rx	Θ= 0°	0.640	0.655	0.670		Note 4 *Color filter Glass With OC
		Ry		0.312	0.327	0.342		
	Green	Gx		0.269	0.284	0.299		
		Gy		0.579	0.594	0.609		
	Blue	Bx		0.123	0.138	0.153		
		By		0.096	0.111	0.126		
White		Wx	Θ= 0°	0.285	0.300	0.315		
		Wy		0.311	0.326	0.341		
Response Time		Tr+Tf	Θ= 0°		30	35	ms	Note 5

Note:

- Viewing angle is the angle at which the contrast ratio is greater than 10. The viewing are determined for the horizontal or 3, 9 o'clock direction and the vertical or 6, 12 o'clock direction with respect to the optical axis which is normal to the LCD surface (see FIG.1).
- Contrast measurements shall be made at viewing angle of $\Theta = 0^\circ$ and at the center of the LCD surface. Luminance shall be measured with all pixels in the view field set first to white, then to the dark (black) state. (See FIG. 1) Luminance Contrast Ratio (CR) is defined mathematically.

$$CR = \frac{\text{Luminance when displaying a white raster}}{\text{Luminance when displaying a black raster}}$$

- Transmittance is the value without APF Pol.
- The color chromaticity coordinates specified in Table1 shall be calculated from



The spectral data measured with all pixels first in red, green, blue and white.

Measurements shall be made at the center of the C/F.

Measurement condition is C - light source & Halogen Lamp

5. The electro-optical response time measurements shall be made as FIG.2 by switching the "data" input signal ON and OFF.

The times needed for the luminance to change from 10% to 90% is T_r , and 90% to 10% is T_f .

Figure 1. Measurement Set Up

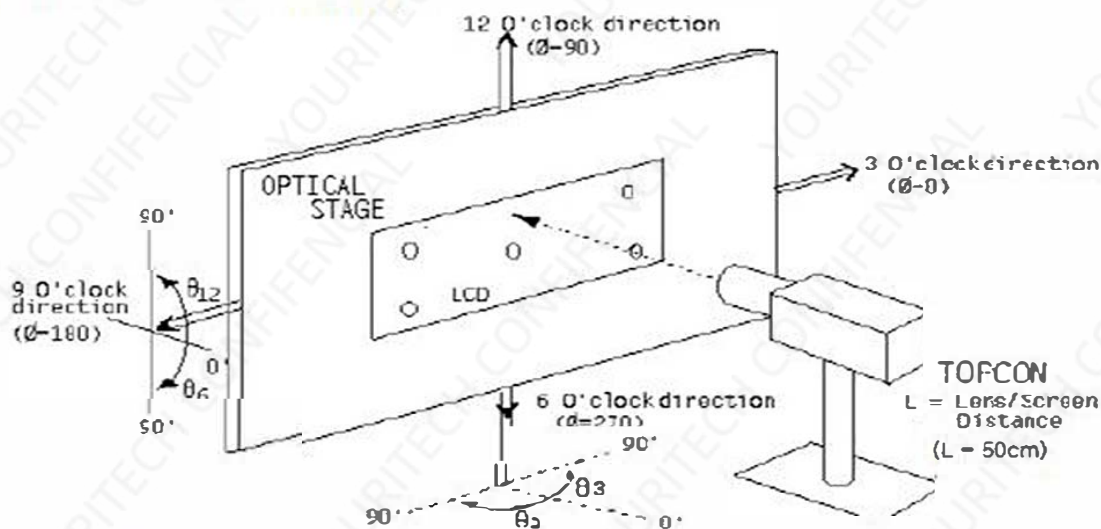
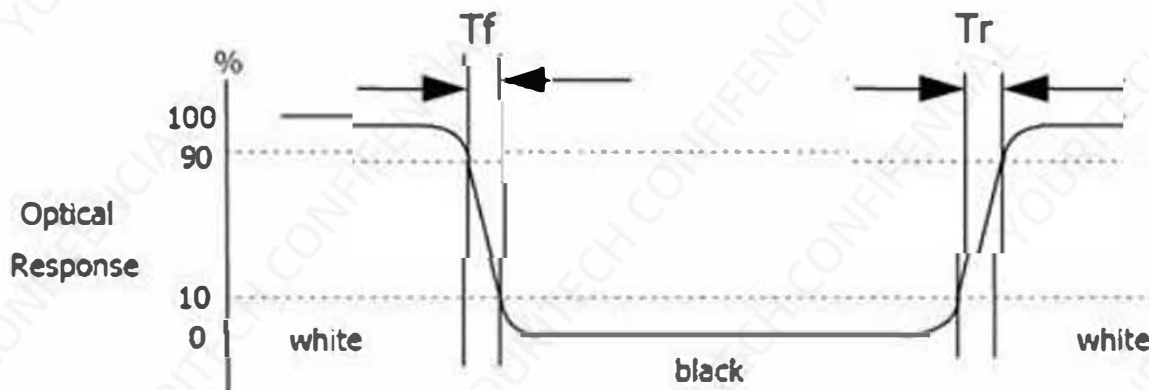


Figure 2. Response Time Testing



8. Reliability Test Item

No.	Test Item	Test Condition	Notes
1	High Temp. Storage	+80°C / 96H	1. Functional test is OK. Missing Segment, short, unclear segment non-display, display abnormally and liquid crystal leakage un-allowed. 2. No low temperature bubbles, end seal loose and fall, frame rainbow.
2	Low Temp. Storage	-30°C / 96H	
3	High Temp. Operating	+70°C / 96H	
4	Low Temp. Operating	-20°C / 96H	
5	High Temperature / Humidity storage	50°C x 90%RH / 96H	
6	Thermal and cold shock	Static state, -20°C (30min) ~70°C (30min), 10 cycles	

9. Packing Method----TBD

- END -

